

SINGLE-SUPPLY, *microPower* CMOS OPERATIONAL AMPLIFIERS

microAmplifier™ Series

FEATURES

- SINGLE-SUPPLY OPERATION
- RAIL-TO-RAIL OUTPUT (within 3mV)
- *microPOWER*: $I_Q = 20\mu\text{A}/\text{Amplifier}$
- *microSIZE* PACKAGES
- LOW OFFSET VOLTAGE: 125 μV max
- SPECIFIED FROM $V_S = 2.3\text{V}$ to 5.5V
- SINGLE, DUAL, AND QUAD VERSIONS

APPLICATIONS

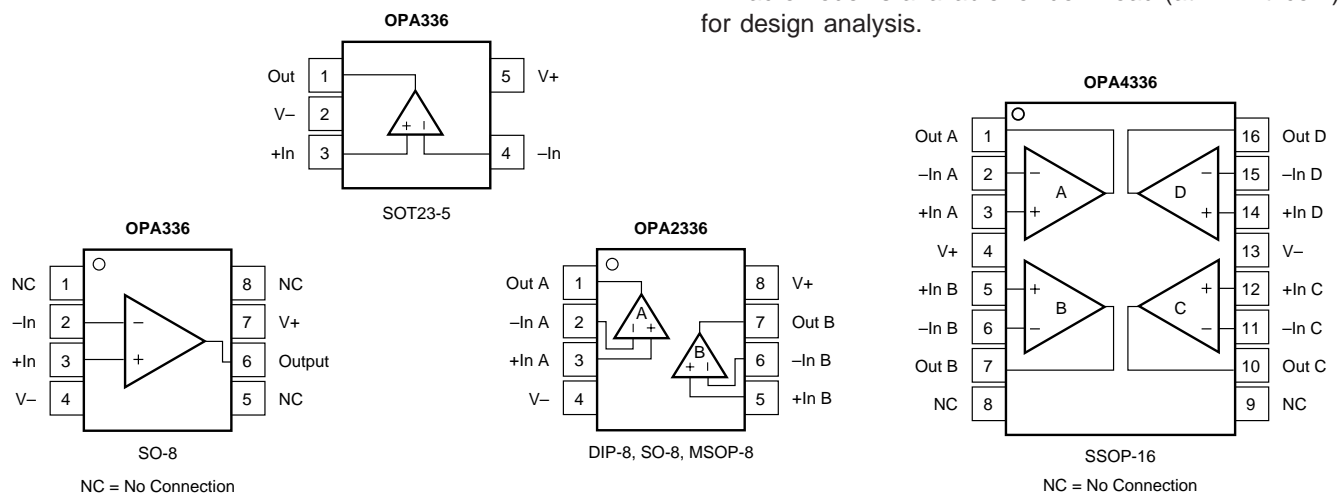
- BATTERY-POWERED INSTRUMENTS
- PORTABLE DEVICES
- HIGH-IMPEDANCE APPLICATIONS
- PHOTODIODE PRE-AMPS
- PRECISION INTEGRATORS
- MEDICAL INSTRUMENTS
- TEST EQUIPMENT

DESCRIPTION

OPA336 series *microPower* CMOS operational amplifiers are designed for battery-powered applications. They operate on a single supply with operation as low as 2.1V. The output is rail-to-rail and swings to within 3mV of the supplies with a 100k Ω load. The common-mode range extends to the negative supply—ideal for single-supply applications. Single, dual, and quad versions have identical specifications for maximum design flexibility.

In addition to small size and low quiescent current (20 $\mu\text{A}/\text{amplifier}$), they feature low offset voltage (125 μV max), low input bias current (1pA), and high open-loop gain (115dB). Dual and quad designs feature completely independent circuitry for lowest crosstalk and freedom from interaction.

OPA336 packages are the tiny SOT23-5 surface mount and SO-8 surface-mount. OPA2336 come in the miniature MSOP-8 surface-mount, SO-8 surface-mount, and DIP-8 packages. The OPA4336 package is the space-saving SSOP-16 surface-mount. All are specified from -40°C to $+85^\circ\text{C}$ and operate from -55°C to $+125^\circ\text{C}$. A macromodel is available for download (at www.ti.com) for design analysis.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

PACKAGE/ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE-LEAD	PACKAGE DRAWING DESIGNATOR	PACKAGE MARKING
Single OPA336N OPA336NA OPA336NJ OPA336U OPA336UA OPA336UJ	SOT23-5 SOT23-5 SOT23-5 SO-8 Surface-Mount SO-8 Surface-Mount SO-8 Surface-Mount	DBV DBV DBV D D D	A36 ⁽²⁾ A36 ⁽²⁾ J36 OPA336U OPA336UA OPA336UJ
Dual OPA2336E OPA2336EA OPA2336P OPA2336PA OPA2336U OPA2336UA	MSOP-8 Surface-Mount MSOP-8 Surface-Mount DIP-8 DIP-8 SO-8 Surface-Mount SO-8 Surface-Mount	DGK DGK P P D D	B36 ⁽²⁾ B36 ⁽²⁾ OPA2336P OPA2336PA OPA2336U OPA2336UA
Quad OPA4336EA	SSOP-16 Surface-Mount	DBQ	OPA4336EA

NOTES: (1) For the most current package and ordering information, see the package option addendum at the end of this data sheet. (2) Grade will be marked on the Reel.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage	7.5V
Signal Input Terminals, Voltage ⁽²⁾	(V-) -0.3V to (V+) +0.3V
Current ⁽²⁾	10mA
Output Short-Circuit ⁽³⁾	Continuous
Operating Temperature	-55°C to +125°C
Storage Temperature	-55°C to +125°C
Junction Temperature	150°C
Lead Temperature (soldering, 10s)	300°C
ESD Rating:	
Charged Device Model, OPA336 NJ and UJ only (CDM) ⁽⁴⁾	1000V
Human Body Model (HBM) ⁽⁴⁾	500V
Machine Model (MM) ⁽⁴⁾	100V

NOTES: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only. Functional operation of the device at these conditions, or beyond the specified operating conditions, is not implied. (2) Input terminals are diode-clamped to the power supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10mA or less. (3) Short-circuit to ground, one amplifier per package. (4) OPA336 NJ and UJ have been tested to CDM of 1000V. All other previous package versions have been tested using HBM and MM. Results are shown.



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ELECTRICAL CHARACTERISTICS: $V_S = 2.3V$ to $5.5V$

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+85^{\circ}C$.

At $T_A = +25^{\circ}C$, $V_S = +5V$, and $R_L = 25k\Omega$ connected to $V_S/2$, unless otherwise noted.

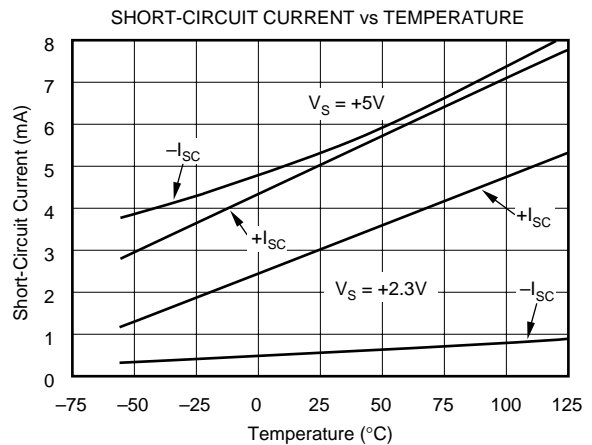
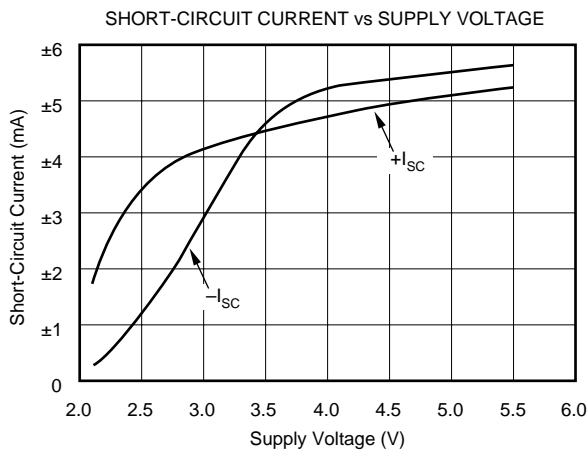
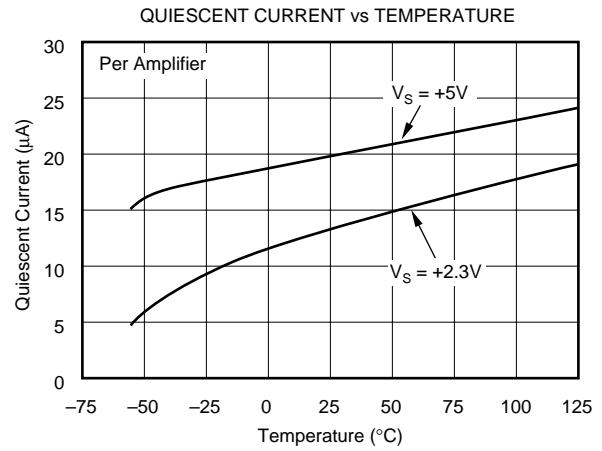
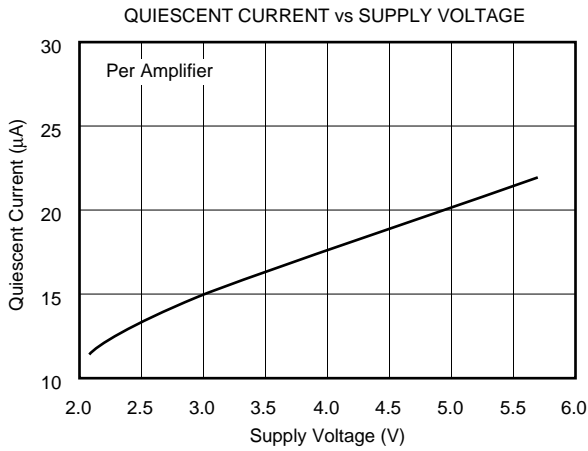
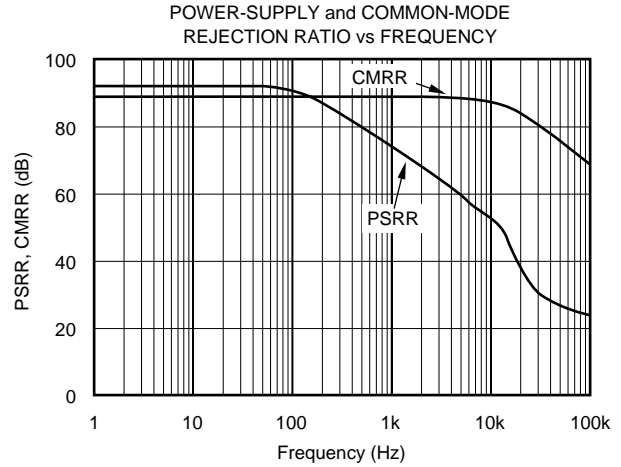
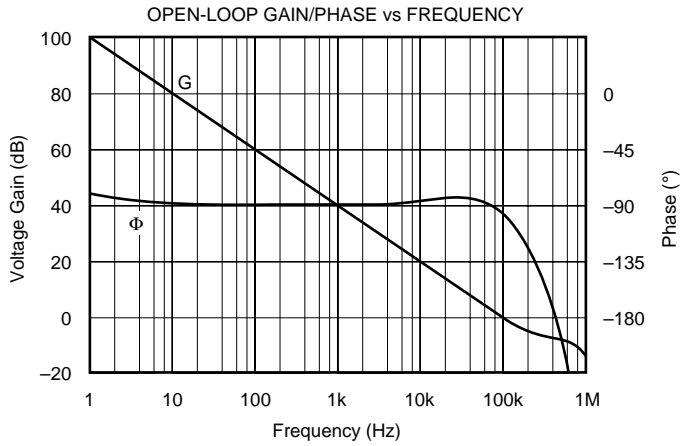
PARAMETER	CONDITION	OPA336N, U OPA2336E, P, U			OPA336NA, UA OPA2336EA, PA, UA OPA4336EA			OPA336NJ, UJ			UNITS
		MIN	TYP ⁽¹⁾	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
OFFSET VOLTAGE Input Offset Voltage vs Temperature vs Power Supply Over Temperature Channel Separation, dc	V_{OS} dV_{OS}/dT PSRR $V_S = 2.3V$ to $5.5V$ $V_S = 2.3V$ to $5.5V$		± 60 ± 1.5 25 0.1	± 125 100 130		* * * *	± 500 * * *		± 500 * * *	± 2500 * * *	μV $\mu V/^{\circ}C$ $\mu V/V$ $\mu V/V$
INPUT BIAS CURRENT Input Bias Current Over Temperature Input Offset Current	I_B I_{OS}		± 1 ± 1	± 10 ± 60 ± 10		* * *	* * *		* * *	* * *	pA pA pA
NOISE Input Voltage Noise, $f = 0.1$ to $10Hz$ Input Voltage Noise Density, $f = 1kHz$ e_n Current Noise Density, $f = 1kHz$ i_n			3 40 30			* * *			* * *		$\mu Vp-p$ nV/\sqrt{Hz} fA/\sqrt{Hz}
INPUT VOLTAGE RANGE Common-Mode Voltage Range Common-Mode Rejection Ratio Over Temperature	V_{CM} CMRR $-0.2V < V_{CM} < (V+) - 1V$ $-0.2V < V_{CM} < (V+) - 1V$	-0.2 80 76	90	$(V+) - 1$	* 76 74	* 86	* *	* 76 74	* 86	* *	V dB dB
INPUT IMPEDANCE Differential Common-Mode			$10^{13} \parallel 2$ $10^{13} \parallel 4$			* *			* *		$\Omega \parallel pF$ $\Omega \parallel pF$
OPEN-LOOP GAIN Open-Loop Voltage Gain Over Temperature Over Temperature	A_{OL} $R_L = 25k\Omega, 100mV < V_O < (V+) - 100mV$ $R_L = 25k\Omega, 100mV < V_O < (V+) - 100mV$ $R_L = 5k\Omega, 500mV < V_O < (V+) - 500mV$ $R_L = 5k\Omega, 500mV < V_O < (V+) - 500mV$	100 100 90 90	115 106		90 90 * *	* * *		90 90 * *	* * *		dB dB dB dB
FREQUENCY RESPONSE Gain-Bandwidth Product Slew Rate Overload Recovery Time	GBW SR $V_S = 5V, G = 1$ $V_S = 5V, G = 1$ $V_{IN} \cdot G = V_S$		100 0.03 100			* * *		* * *			kHz V/ μs μs
OUTPUT Voltage Output Swing from Rail ⁽²⁾ Over Temperature Over Temperature Short-Circuit Current Capacitive Load Drive	$R_L = 100k\Omega, A_{OL} \geq 70dB$ $R_L = 25k\Omega, A_{OL} \geq 90dB$ $R_L = 25k\Omega, A_{OL} \geq 90dB$ $R_L = 5k\Omega, A_{OL} \geq 90dB$ $R_L = 5k\Omega, A_{OL} \geq 90dB$		3 20 70 ± 5 See Text	100 100 500 500		* * * * *		* * * * *	* * * * *		mV mV mV mV mA pF
POWER SUPPLY Specified Voltage Range Minimum Operating Voltage Quiescent Current (per amplifier) Over Temperature	V_S I_Q $I_O = 0$ $I_O = 0$	2.3	2.1 20	5.5 32 36	* * * *	* * * *	* * * *	* * * *	* 23 38 42		V V μA μA
TEMPERATURE RANGE Specified Range Operating Range Storage Range Thermal Resistance SOT-23-5 Surface-Mount MSOP-8 Surface-Mount SO-8 Surface-Mount DIP-8 SSOP-16 Surface-Mount DIP-14	θ_{JA}	-40 -55 -55		$+85$ $+125$ $+125$	* * *	* * *	* * *	* * *	* * * * * * *		$^{\circ}C$ $^{\circ}C$ $^{\circ}C$ $^{\circ}C/W$ $^{\circ}C/W$ $^{\circ}C/W$ $^{\circ}C/W$ $^{\circ}C/W$ $^{\circ}C/W$

*Specifications same as OPA2336E, P, U.

NOTES: (1) $V_S = +5V$. (2) Output voltage swings are measured between the output and positive and negative power-supply rails.

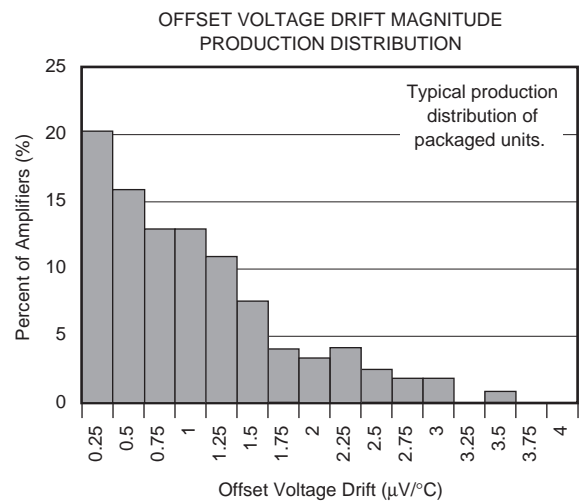
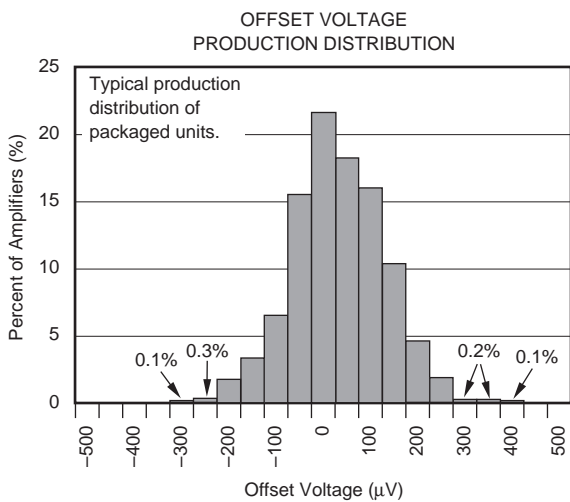
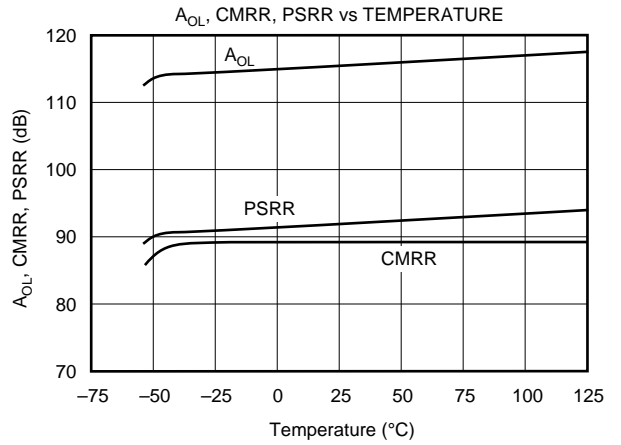
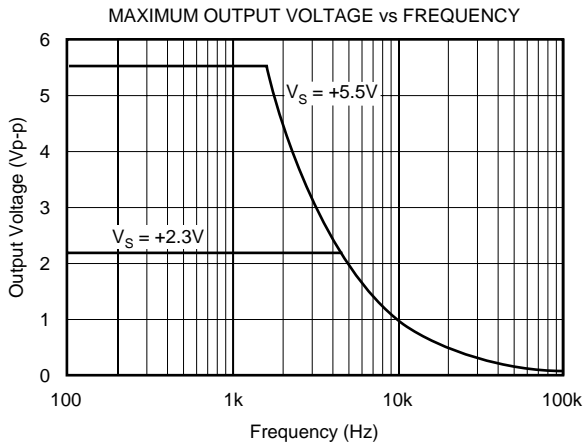
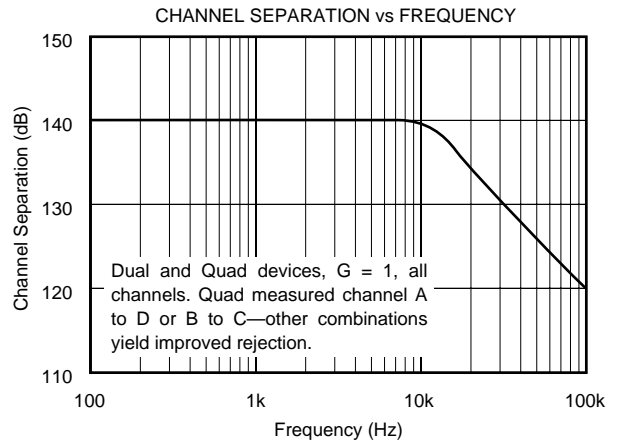
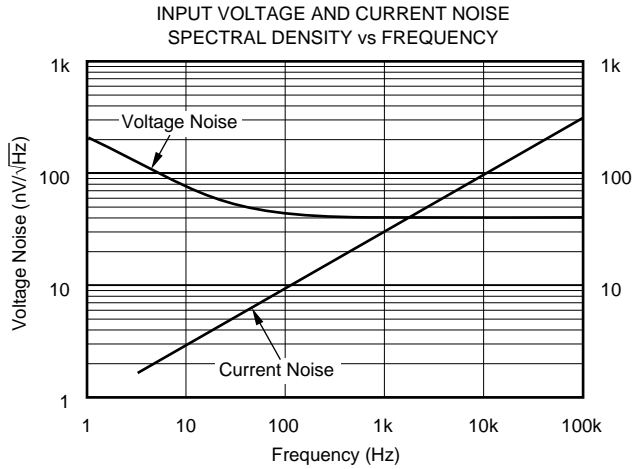
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_S = +5\text{V}$, and $R_L = 25\text{k}\Omega$ connected to $V_S/2$, unless otherwise noted.



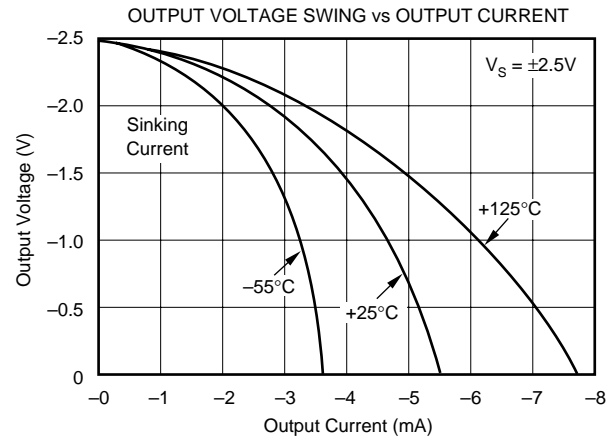
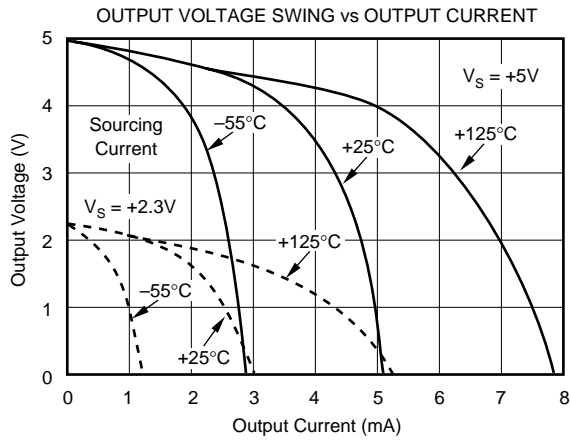
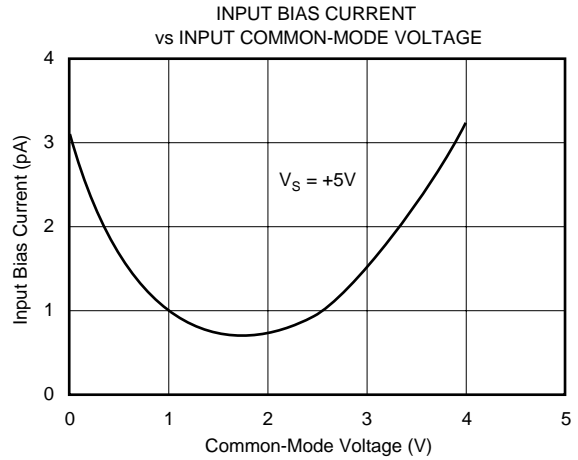
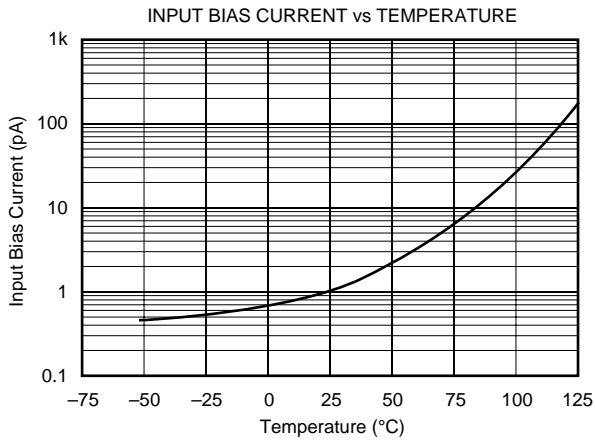
TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$, $V_S = +5\text{V}$, and $R_L = 25\text{k}\Omega$ connected to $V_S/2$, unless otherwise noted.

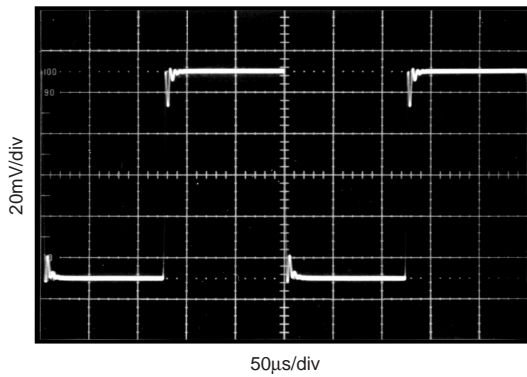


TYPICAL CHARACTERISTICS (Cont.)

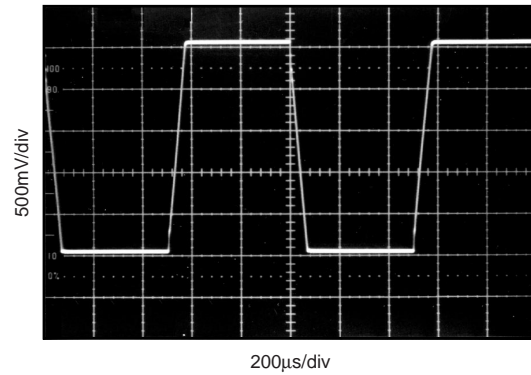
At $T_A = +25^\circ\text{C}$, $V_S = +5\text{V}$, and $R_L = 25\text{k}\Omega$ connected to $V_S/2$, unless otherwise noted.



SMALL-SIGNAL STEP RESPONSE
 $G = 1$, $C_L = 200\text{pF}$, $V_S = +5\text{V}$



LARGE-SIGNAL STEP RESPONSE
 $G = 1$, $C_L = 620\text{pF}$, $V_S = +5\text{V}$



APPLICATIONS INFORMATION

OPA336 series op amps are fabricated on a state-of-the-art 0.6 micron CMOS process. They are unity-gain stable and suitable for a wide range of general-purpose applications. Power-supply pins should be bypassed with 0.01μF ceramic capacitors. OPA336 series op amps are protected against reverse battery voltages.

OPERATING VOLTAGE

OPA336 series op amps can operate from a +2.1V to +5.5V single supply with excellent performance. Most behavior remains unchanged throughout the full operating voltage range. Parameters which vary significantly with operating voltage are shown in the typical characteristics. OPA336 series op amps are fully specified for operation from +2.3V to +5.5V; a single limit applies over the supply range. In addition, many parameters are ensured over the specified temperature range, -40°C to +85°C.

INPUT VOLTAGE

The input common-mode range of OPA336 series op amps extends from (V-) - 0.2V to (V+) - 1V. For normal operation, inputs should be limited to this range. The absolute maximum input voltage is 300mV beyond the supplies. Thus, inputs greater than the input common-mode range but less than maximum input voltage, while not valid, will not cause any damage to the op amp. Furthermore, the inputs may go beyond the power supplies without phase inversion, as shown in Figure 1, unlike some other op amps.

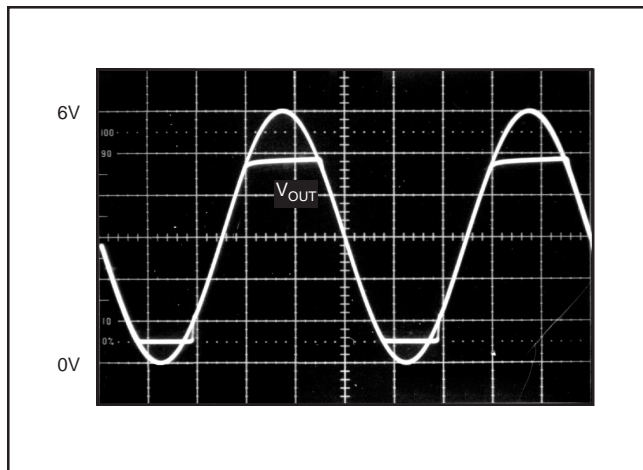


FIGURE 1. No Phase Inversion with Inputs Greater than the Power-Supply Voltage.

Normally, input bias current is approximately 1pA. However, input voltages exceeding the power supplies can cause excessive current to flow in or out of the input pins. Momentary voltages greater than the power supply can be tolerated as long as the current on the input pins is limited to 10mA. This is easily accomplished with an input resistor, as shown in Figure 2.

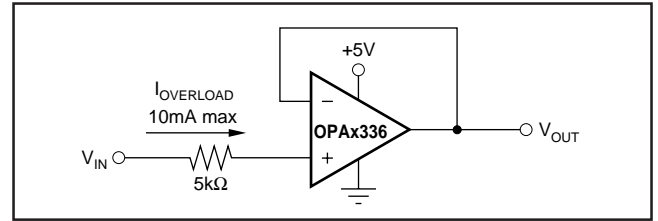


FIGURE 2. Input Current Protection for Voltages Exceeding the Supply Voltage.

CAPACITIVE LOAD AND STABILITY

OPA336 series op amps can drive a wide range of capacitive loads. However, all op amps under certain conditions may become unstable. Op-amp configuration, gain, and load value are just a few of the factors to consider when determining stability.

When properly configured, OPA336 series op amps can drive approximately 10,000pF. An op amp in unity-gain configuration is the most vulnerable to capacitive load. The capacitive load reacts with the op amp's output resistance, along with any additional load resistance, to create a pole in the response which degrades the phase margin. In unity gain, OPA336 series op amps perform well with a pure capacitive load up to about 300pF. Increasing gain enhances the amplifier's ability to drive loads beyond this level.

One method of improving capacitive load drive in the unity-gain configuration is to insert a 50Ω to 100Ω resistor inside the feedback loop, as shown in Figure 3. This reduces ringing with large capacitive loads while maintaining DC

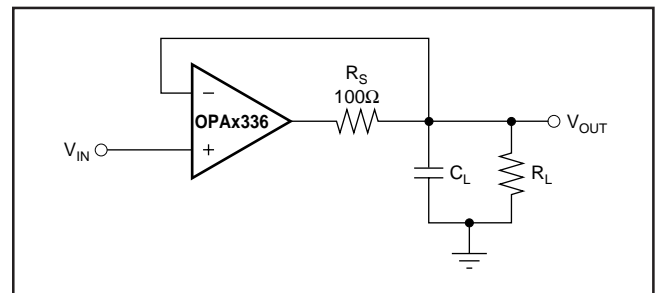


FIGURE 3. Series Resistor in Unity-Gain Configuration Improves Capacitive Load Drive.

accuracy. For example, with $R_L = 25\text{k}\Omega$, OPA336 series op amps perform well with capacitive loads in excess of 1000pF , as shown in Figure 4. Without R_S , capacitive load drive is typically 350pF for these conditions, as shown in Figure 5.

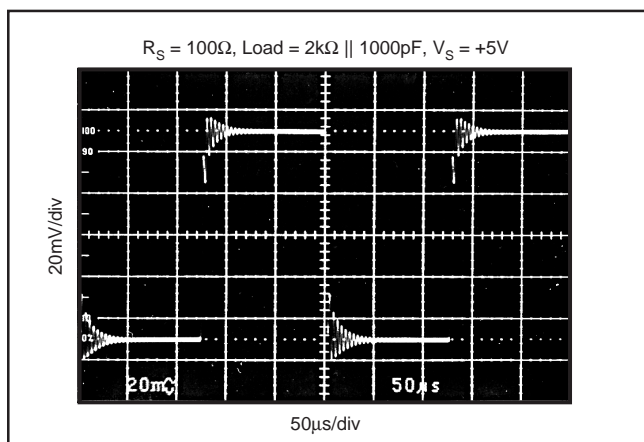


FIGURE 4. Small-Signal Step Response Using Series Resistor to Improve Capacitive Load Drive.

Alternatively, the resistor may be connected in series with the output outside of the feedback loop. However, if there is a resistive load parallel to the capacitive load, it and the series resistor create a voltage divider. This introduces a

Direct Current (DC) error at the output; however, this error may be insignificant. For instance, with $R_L = 100\text{k}\Omega$ and $R_S = 100\Omega$, there is only about a 0.1% error at the output.

Figure 5 shows the recommended operating regions for the OPA336. Decreasing the load resistance generally improves capacitive load drive. Figure 5 also illustrates how stability differs depending on where the resistive load is connected. With $G = +1$ and $R_L = 10\text{k}\Omega$ connected to $V_S/2$, the OPA336 can typically drive 500pF . Connecting the same load to ground improves capacitive load drive to 1000pF .

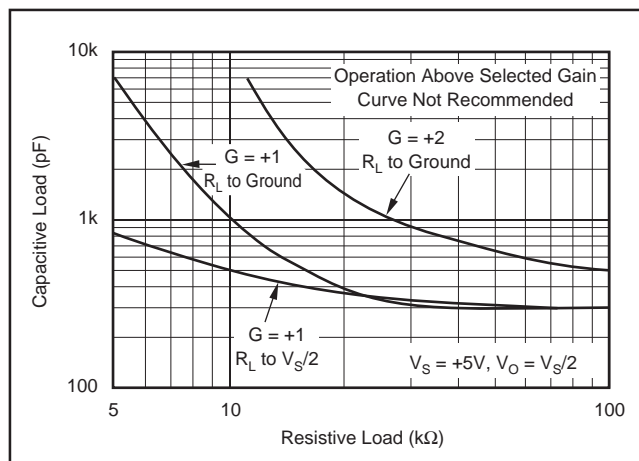


FIGURE 5. Stability—Capacitive Load vs Resistive Load.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
OPA2336E/250	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336E/250G4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336E/2K5	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336E/2K5G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336EA/250	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336EA/250G4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336EA/2K5	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336EA/2K5G4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336P	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2336PA	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2336PAG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2336PG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
OPA2336U	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336UA	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336UAG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2336UG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336N/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336N/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336N/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336N/3KG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336NA/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
OPA336NA/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336NA/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336NA/3KG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336NJ/250	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336NJ/250G4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336NJ/3K	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336NJ/3KG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
OPA336P	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI
OPA336PA	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI
OPA336U	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336U/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336U/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336UA	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336UA/2K5	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336UA/2K5G4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336UAG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA336UG4	ACTIVE	SOIC	D	8	100	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA4336EA/250	ACTIVE	SSOP/ QSOP	DBQ	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA4336EA/250G4	ACTIVE	SSOP/ QSOP	DBQ	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA4336EA/2K5	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA4336EA/2K5G4	ACTIVE	SSOP/ QSOP	DBQ	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA4336PA	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF OPA336 :

- Enhanced Product: [OPA336-EP](#)

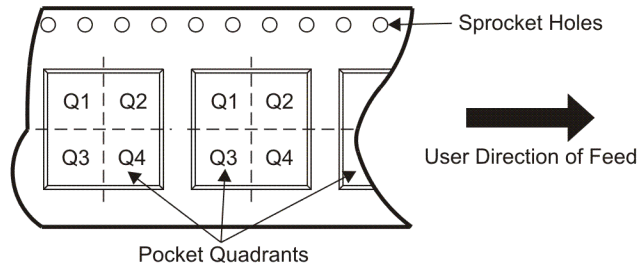
NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2336E/250	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2336E/2K5	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2336EA/250	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2336EA/2K5	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2336U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2336UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA336U/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA336UA/2K5	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4336EA/250	SSOP/QSOP	DBQ	16	250	180.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA4336EA/2K5	SSOP/QSOP	DBQ	16	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

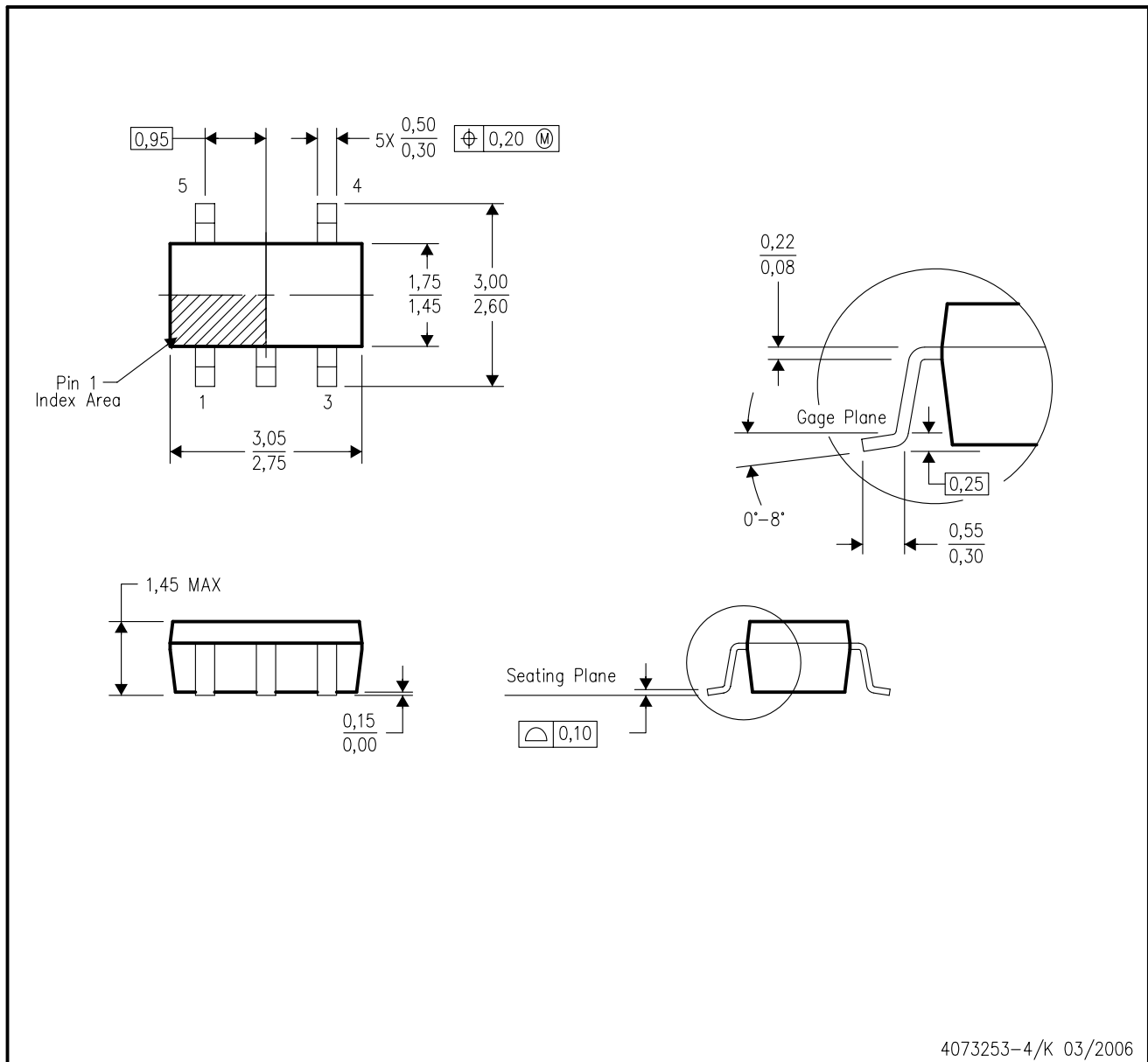


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2336E/250	MSOP	DGK	8	250	184.0	184.0	50.0
OPA2336E/2K5	MSOP	DGK	8	2500	346.0	346.0	29.0
OPA2336EA/250	MSOP	DGK	8	250	184.0	184.0	50.0
OPA2336EA/2K5	MSOP	DGK	8	2500	346.0	346.0	29.0
OPA2336U/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA2336UA/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA336U/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA336UA/2K5	SOIC	D	8	2500	346.0	346.0	29.0
OPA4336EA/250	SSOP/QSOP	DBQ	16	250	190.5	212.7	31.8
OPA4336EA/2K5	SSOP/QSOP	DBQ	16	2500	346.0	346.0	29.0

DBV (R-PDSO-G5)

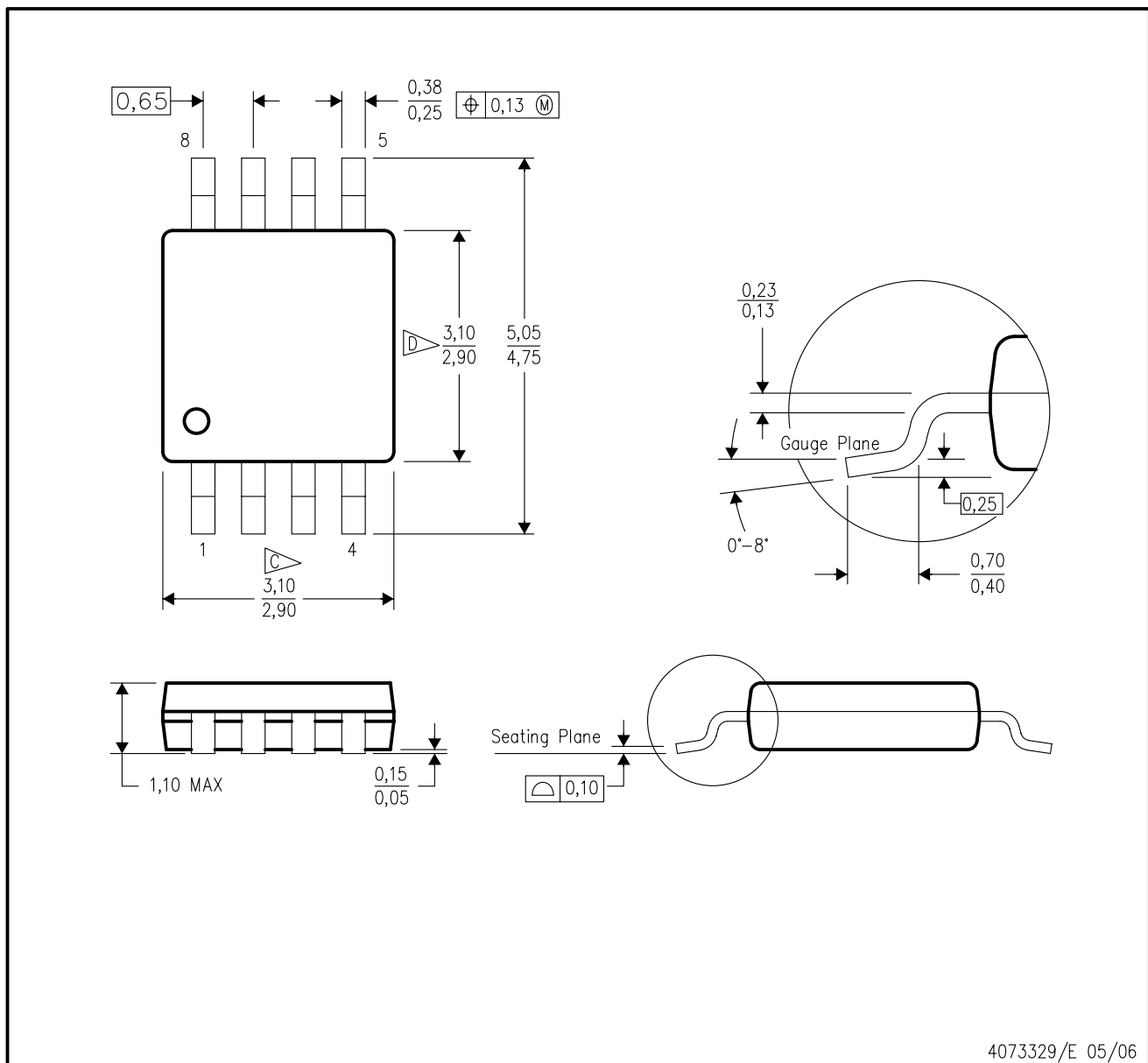
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DGK (S-PDSO-G8)

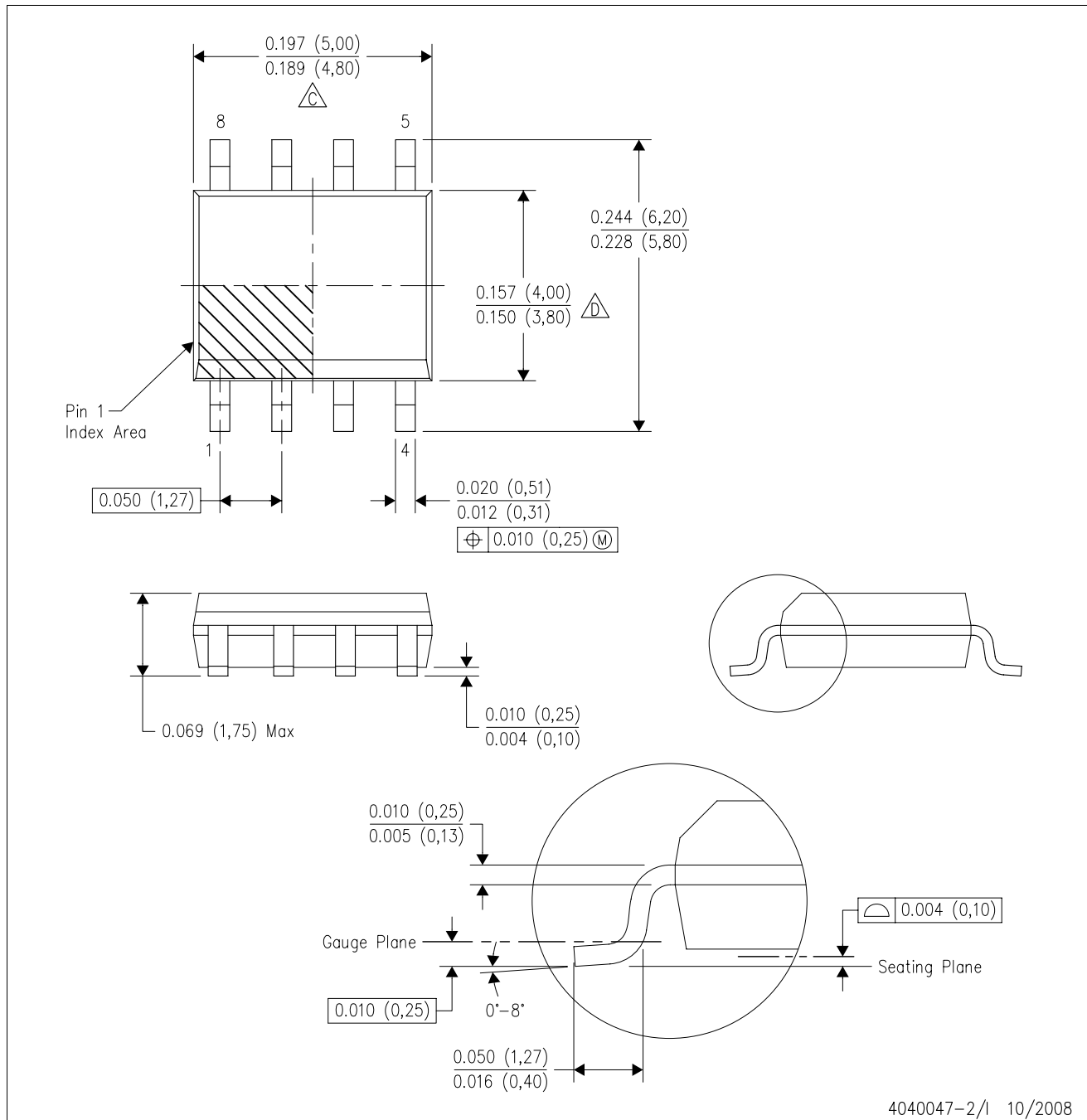
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
 - Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
 - Falls within JEDEC MO-187 variation AA, except interlead flash.

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE

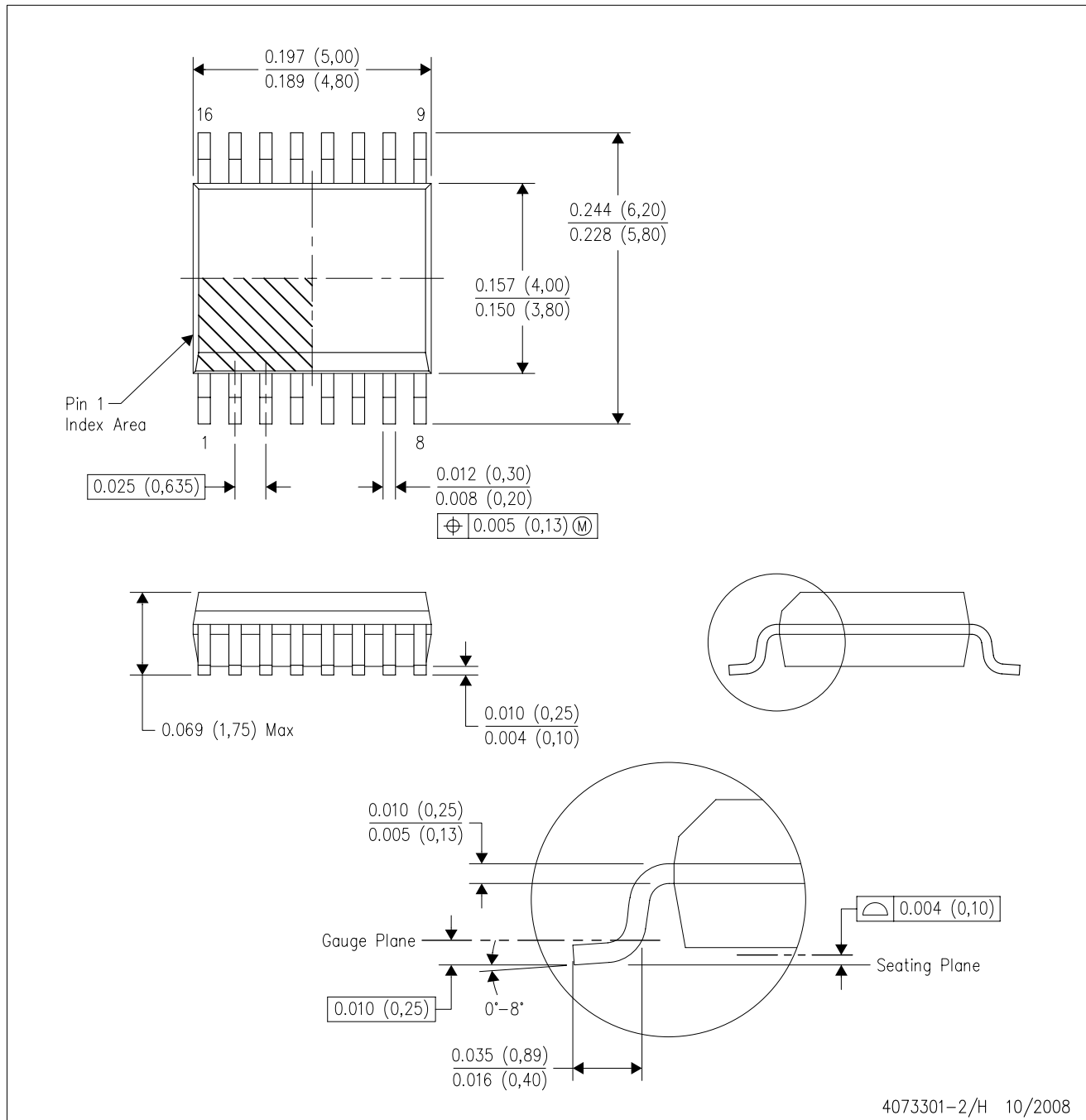


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

DBQ (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AB.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated